

Thermal stabilities and dynamic mechanical properties of dielectric materials for next generation PCB

조재춘, 이화영, 임성택, 박문수, 이근용, 오준록
삼성전기 중앙연구소 eMD 센터

Samsung electro-mechanics Co., LTD, Central R&D Institute, eMD Lab
Jaechoon Cho, Hyayoung Lee, Sungtaek Lim, Moonsu Park, Keunyong Lee, Junlok Oh

Abstract : Recently, high performance microelectronic devices are designed in multi-layer structure in order to make dense wiring of metal conductors in compact size. For making dense wiring of metal conductors, we investigated CTE and peel strength of dielectric materials for next generation PCB. It is an object of this research to develop an epoxy resin composition for an interlayer insulating material exhibiting low CTE and high peel strength and making an insulating layer thinner.